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# PN5180A0xx/C1/C2

High-performance multi-protocol full NFC frontend, supporting all NFC Forum modes

Rev. 3.6 — 7 May 2018 240936 Product data sheet COMPANY PUBLIC

# 1 Introduction

This document describes the functionality and electrical specification of the high-power NFC IC PN5180A0HN/C1, PN5180A0ET/C1,PN5180A0HN/C2, PN5180A0ET/C2.

Additional documents supporting a design-in of the PN5180 are available from NXP, this information is not part of this document.



# 2 General description

PN5180, the best full NFC frontend on the market.

As a highly integrated high performance full NFC Forum-compliant frontend IC for contactless communication at 13.56 MHz, this frontend IC utilizes an outstanding modulation and demodulation concept completely integrated for different kinds of contactless communication methods and protocols.

The PN5180 ensures maximum interoperability for next generation of NFC enabled mobile phones. The PN5180 is optimized for point of sales terminal applications and implements a high-power NFC frontend functionality which allows to achieve EMV compliance on RF level without additional external active components.

The PN5180 frontend IC supports the following RF operating modes:

- Reader/Writer mode supporting ISO/IEC 14443 type A up to 848 kBit/s
- Reader/Writer communication mode for MIFARE Classic contactless IC
- Reader/Writer mode supporting ISO/IEC 14443 type B up to 848 kBit/s
- Reader/Writer mode supporting JIS X 6319-4 (comparable with FeliCa scheme)
- Supports reading of all NFC tag types (type 1, type 2, type 3, type 4A and type 4B)
- Reader/Writer mode supporting ISO/IEC 15693
- Reader/Writer mode supporting ISO/IEC 18000-3 Mode 3
- ISO/IEC 18092 (NFC-IP1)
- ISO/IEC 21481 (NFC-IP-2)
- ISO/IEC 14443 type A Card emulation up to 848 kBit/s

One host interface based on SPI is implemented:

- SPI interface with data rates up to 7 Mbit/s with MOSI, MISO, NSS and SCK signals
- Interrupt request line to inform host controller on events
- EEPROM configurable pull-up resistor on SPI MISO line
- · Busy line to indicate to host availability of data for reading

The PN5180 supports highly innovative and unique features which do not require any host controller interaction. These unique features include Dynamic Power Control (DPC), Adaptive Waveform Control (AWC), Adaptive Receiver Control (ARC), and fully automatic EMD error handling. The independency of real-time host controller interactions makes this product the best choice for systems which operate a preemptive multi-tasking OS like Linux or Android.

As new power-saving feature the PN5180 allows using a general-purpose output to control an external LDO or DC/DC during Low-Power Card Detection. One general-purpose output is used to wake-up an LDO or DC/DC from power-saving mode before the RF field for an LPCD polling cycle is switched on.

The PN5180 supports an external silicon system-power-on switch by using the energy of the RF field generated by an NFC phone to switch on the system, like it is generated during the NFC polling loop. This unique and new Zero-Power-Wake-up feature allows designing systems with a power consumption close to zero during standby.

### 3 Features and benefits

- Transmitter current up to 250 mA
- Dynamic Power Control (DPC) for optimized RF performance, even under detuned antenna conditions
- Adaptive Waveform Control (AWC) automatically adjusts the transmitter modulation for RF compliancy
- Adaptive Receiver Control (ARC) automatically adjusts the receiver parameters for always reliable communication
- Includes NXP ISO/IEC14443 type A and Innovatron ISO/IEC14443 type B intellectual property licensing rights
- Full compliancy with all standards relevant to NFC, contactless operation and EMVCo
- · Active load modulation supports smaller antenna in Card Emulation Mode
- Automatic EMD handling performed without host interaction relaxes the timing requirements on the Host Controller
- Low-power card detection (LPCD) minimizes current consumption during polling
- Automatic support of system LDO or system DC/DC power-down mode during LPCD
- · Zero-Power-Wake-up
- Small, industry-standard packages
- NFC Cockpit: PC-based support tool for fast configuration of register settings
- Development kit with 32-bit NXP LPC1769 MCU and antenna
- NFC Reader Library with source code ready for EMVCo L1 and NFC Forum compliance

# 4 Applications

- Payment
- · Physical-access
- eGov
- Industrial

# 5 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V <sub>DD(VBAT)</sub>	supply voltage on pin VBAT	-	2.7	3.3	5.5	V
V <sub>DD(PVDD)</sub> su	supply voltage on pin PVDD	1.8 V supply	1.65	1.8	1.95	V
		3.3 V supply	2.7	3.3	3.6	V
V <sub>DD(TVDD)</sub>	supply voltage on pin TVDD	-	2.7	5.0	5.5	V
I <sub>pd</sub>	power-down current	VDD(TVDD) = VDD(PVDD) =VDD(VDD) 3.0 V; hard power-down; pin RESET_N set LOW, T <sub>amb</sub> = 25 °C	-	10	-	μА
I <sub>stb</sub>	standby current	T <sub>amb</sub> = 25 °C	-	15	-	μA
I <sub>DD(TVDD)</sub> supply current on pin TV		-	-	180	250	mA
		limiting value	-	-	300	mA
T <sub>amb</sub>	ambient temperature	in still air with exposed pins soldered on a 4 layer JEDEC PCB	-30	+25	+85	°C
T <sub>stg</sub>	storage temperature	no supply voltage applied	-55	+25	+150	°C

# 6 Versions

All firmware versions smaller or equal to Verrion 3.9 are covered by this document.

Firmware versions larger than Version 3.9 are covered by a dedicated document.

Available firmware versions:

# Version 3.4: Allows EMVCO 2.3.1 compliant EMD error handling

Version information:

- EEPROM address 0x12: 0x04
- EEPROM address 0x13: 0x03

# Version 3.5: Allows EMVCO 2.5 compliant EMD error handling

Version information:

- EEPROM address 0x12: 0x05
- EEPROM address 0x13: 0x03

Changes of Version 3.5 compared to Version 3.4:

- The EMD CONTROL register is updated to support EMVCo 2.5.
- · Adaptive Waveform Control (AWC) implemented

### **Version 3.6: Automatic Receiver Control added**

No silicon initialized with this firmware is available. Usage of this firmware requires an update by the user.

Version information:

- EEPROM address 0x12: 0x06
- EEPROM address 0x13: 0x03

Changes of Version 3.6 compared to Version 3.5:

- Accessible EEPROM top address is changed to 0xFE
- EEPROM functional assignment starting at address 0xD8
- EEPROM updates to support using GPO1 during LPCD card detect and GPIO2 during wake-up from standby
- Adaptive Receiver configuration (ARC) available: EEPROM table updates for receiver configuration
- Energy of external RF field can be used to operate an external system-power-on switch

#### Version 3.7: Not released

### Version 3.8: Firmware version prepared for EMVCo 2.6

Changes of Version 3.6 compared to Version 3.8:

- EEPROM configuration for PLL\_DEFAULT\_SETTING (address 0x1C) had been updated with timer options and persistent testbus configuration added
- LDO\_OUT pin is available for output of regulated 3.3V, configuration options added to SYSTEM\_CONFIG register; SYSTEM\_STATUS register is extended by bit LDO\_TVDD\_OK. THIS FEATURE CAN BE ENABLED ON ALL PN5180 PRODUCT

PN5180

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VERSIONS. PRODUCTION TEST OF THIS FEATURE IS PERFORMED ON PN5180A0HN/C3 AND PN5180A0ET/C3 ONLY.

- ACTIVE MODE TX RF ENABLE added to SYSTEM CONFIG register
- The EMD block offers the possibility to stop and restart a CLIF Timer. This selection
  can be done via register. The firmware 3.8 allows usage of any timer (T0, T1 or T2) as
  CLIF timer.
- · prepared for EMVCo. 2.6 digital compliancy

#### Version 3.9:

The DPC\_XI can be configured in the RAM using SYSTEM\_CONFIG, which is used along with the AGC\_XI in EEPROM for AGC correction. The DPC\_XI in RAM can be used using enable/disable bit in EEPROM. This allows to compensate a temperature shift of the AGC to improve the accuracy of the DPC. (The temperature can be measured externally by the host  $\mu$ C.)

- SYSTEM\_CONFIG register bits in range[12-19] are used to configure the 8bit DPC\_XI value in RAM
- In EEPROM, Dynamic DPC\_Xi RAM can be enabled/disabled using EEPROM Misc\_Config, bit 5

# 7 Ordering information

**Table 2. Ordering information** 

Type number	Package		
	Name	Description	Version
PN5180A0HN/C1E	HVQFN40	Firmware version 3.4. Plastic thermal enhanced very thin quad flat package; no leads; 40 terminals + 1 central ground; body 6 x 6 x 1.0 mm; delivered in one tray, bakable, MSL=3. Minimum order quantity = 490 pcs	SOT618-1
PN5180A0HN/C1Y	HVQFN40	Firmware version 3.4. Plastic thermal enhanced very thin quad flat package; no leads; 40 terminals + 1 central ground; body 6 x 6 x 1.0 mm; delivered on reel 13", MSL = 3. Minimum order quantity = 4000 pcs	SOT618-1
PN5180A0ET/C1QL	TFBGA64	Firmware version 3.4. Plastic thin fine-pitch ball grid array package; 64 balls, delivered in one tray, MSL = 1. Minimum order quantity = 490 pcs	SOT1336-1
PN5180A0ET/C1J	TFBGA64	Firmware version 3.4. Plastic thin fine-pitch ball grid array package; 64 balls, delivered on reel 13", MSL = 1. Minimum order quantity = 4000 pcs	SOT1336-1
PN5180A0HN/C2E	HVQFN40	Firmware version 3.5. Plastic thermal enhanced very thin quad flat package; no leads; 40 terminals + 1 central ground; body 6 x 6 x 1.0 mm; delivered in one tray, bakable, MSL=3. Minimum order quantity = 490 pcs	SOT618-1
PN5180A0HN/C2Y	HVQFN40	Firmware version 3.5. Plastic thermal enhanced very thin quad flat package; no leads; 40 terminals + 1 central ground; body 6 x 6 x 1.0 mm; delivered on reel 13", MSL = 3. Minimum order quantity = 4000 pcs	SOT618-1
PN5180A0ET/C2QL	TFBGA64	Firmware version 3.5. Plastic thin fine-pitch ball grid array package; 64 balls, delivered in one tray, MSL = 1. Minimum order quantity = 490 pcs	SOT1336-1
PN5180A0ET/C2J	TFBGA64	Firmware version 3.5. Plastic thin fine-pitch ball grid array package; 64 balls, delivered on reel 13", MSL = 1. Minimum order quantity = 4000 pcs	SOT1336-1

The PN5180 is not available with pre-installed firmware version 3.6, 3.7, 3.8 and 3.9

# 8 Marking

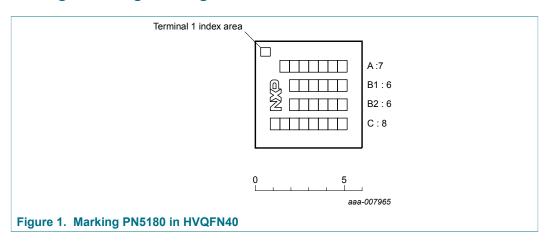
Table 3. Marking codes HVQFN40

Type number  NS180 (first engineering prototypes)  Line A: These devices are intended for prototype development only,  Line B1:  "01 01" or 6 characters: Diffusion Batch ID and assembly sequence ID  Line B2:  Line C: Engineering prototypes are marked "Product life cycle status code Before CQS": X  Product life cycle status code Before CQS": X  Line C: Engineering prototypes are marked "Product life cycle status code Before CQS": X  Ribert Code, product version (indicated by mask version), product life cycle status. This line includes the following elements at 8 positions:  1. Diffusion center code 2. Assembly center code 3. RHF-2006 indicator 4. Year code (W) 2) 6. Week code (W) 2) 7. Mask layout version 8. (Product life cycle status code "Before CQS")  X  PNS180 (customer qualification samples)  Line B1:  Line B2:  Line C: Customer qualification samples are marked as CQS: X or Y  PNS180 (sustomer qualification samples are marked as CQS: X or Y  Reproduct life cycle status and assembly location, date code, product version (indicated by mask version), product life cycle status. This line includes the following elements at 8 positions:  1. Diffusion center code 2. Assembly center code 3. RHF-2006 indicator 4. Year code (W) 2) 7. Mask layout version (indicated by mask version), product life cycle status. This line includes the following elements at 8 positions:  1. Diffusion center code 3. RHF-2006 indicator 4. Year code (W) 2) 7. Mask layout version (indicated by mask version), product life cycle status. This line includes the following elements at 8 positions:  1. Diffusion center code 3. RHF-2006 indicator 4. Year code (W) 2) 7. Mask layout version (indicated by mask version), product life cycle status code "CQS"): X or Y  PNS180A0HN (released for sale: volume production)  Line A:  Line B1:  Line B2:  Assembly sequence ID. example ".1 04"	Table 3. Marking codes HVQFN40	
Line A: These devices are intended for prototype development only.  Line B1:  "01 01" or 6 characters: Diffusion Batch ID and assembly sequence ID  "FW 1.1" or "Z.1 01"  8 characters: diffusion and assembly location, date code, product life cycle status. This line includes the following elements at 8 positions:  1. Diffusion center code 2. Assembly center code 3. RHF-2006 indicator 4. Year code (W) 2) 7. Mask layout version 8. (Product life cycle status code "Before CQS")  PN5180 (customer qualification samples)  Line A:  Line B1:  Cine B2:  Line C: Customer qualification samples are marked as CQS: X or Y  PN5180 (customer qualification samples are marked as CQS: X or Y  PN5180 (customer qualification samples are marked as CQS: X or Y  PN5180 (customer qualification samples are marked as CQS: X or Y  PN5180 (customer qualification samples are marked as CQS: X or Y  PN5180 (customer qualification samples are marked as CQS: X or Y  PN5180 (customer qualification samples are marked as CQS: X or Y  PN5180 (customer qualification samples are marked as CQS: X or Y  PN5180 (customer qualification samples are marked as CQS: X or Y  PN5180 (customer qualification samples are marked as CQS: X or Y  PN5180 (customer qualification samples are marked as CQS: X or Y  PN5180 (customer qualification samples are marked as CQS: X or Y  PN5180 (customer qualification samples are marked as CQS: X or Y  PN5180 (customer qualification samples are marked as CQS: X or Y  PN5180 (customer qualification samples are marked as CQS: X or Y  PN5180 (customer qualification samples are marked as CQS: X or Y  PN5180 (customer qualification samples are marked as CQS: X or Y  PN5180 (customer qualification samples are marked as CQS: X or Y  PN5180 (customer qualification samples are marked as CQS: X or Y  PN5180 (customer qualification samples are marked as CQS: X or Y  PN5180 (customer qualification samples are marked as CQS: X or Y  PN5180 (customer qualification samples are marked as CQS: X or Y  PN5180 (customer qualification samples are	Type number	Marking code
prototype development only,  Line B1:  "01 01" or 6 characters: Diffusion Batch ID and assembly sequence ID  "FW 1.1" or "Z.1 01"  Regional assembly sequence ID  "FW 1.1" or "Z.1 01"  8 characters: diffusion and assembly location, date code, product version (indicated by mask version), product life cycle status. This line includes the following elements at 8 positions:  1. Diffusion center code  2. Assembly center code  3. RHF-2006 indicator  4. Year code (W) 2)  6. Week code (W) 2)  7. Mask layout version  8. (Product life cycle status code "Before CQS")  X  PN5180 (customer qualification samples)  Line A:  Line B1:  6 characters: Diffusion Batch ID and assembly sequence ID  blank  Line C: Customer qualification samples are marked as CQS: X or Y  8 characters: diffusion and assembly location, date code, product version (indicated by mask version), product life cycle status. This line includes the following elements at 8 positions:  1. Diffusion center code  2. Assembly center code  2. Assembly center code  3. RHF-2006 indicator  4. Year code (W) 2)  6. Week code (W) 2)  7. Mask layout version  8. Characters: diffusion and assembly location, date code, product life cycle status. This line includes the following elements at 8 positions:  1. Diffusion center code  2. Assembly center code  3. RHF-2006 indicator  4. Year code (W) 2)  6. Week code (W) 2)  7. Mask layout version  8. (Product life cycle status code "CQS"): X or Y  PN5180AOHN (released for sale: volume production)  Line A:  Line B1:  6 characters: Diffusion Batch ID	PN5180 (first engineering prototypes)	
and assembly sequence ID  Line B2:  "FW 1.1" or "Z.1 01"  8 characters: diffusion and assembly location, date code, product version (indicated by mask version), product life cycle status code Before CQS": X version), product life cycle status. This line includes the following elements at 8 positions:  1. Diffusion center code 2. Assembly center code 3. RHF-2006 indicator 4. Year code (W) 2) 6. Week code (W) 2) 7. Mask layout version 8. (Product life cycle status code "Before CQS") X  PN5180 (customer qualification samples)  Line A:  Line B1:  6 characters: Diffusion Batch ID and assembly sequence ID  blank  Line B2:  Line C: Customer qualification samples are marked as CQS: X or Y  Batch and a sembly location, date code, product version (indicated by mask version), product life cycle status. This line includes the following elements at 8 positions: 1. Diffusion center code 2. Assembly center code 3. RHF-2006 indicator 4. Year code (Y) 1) 5. Week code (W) 2) 6. Week code (W) 2) 7. Mask layout version 8. (Product life cycle status code "CQS"): X or Y  PN5180A0HN (released for sale: volume production)  Line A:  PN5180A  C characters: Diffusion Batch ID		PN51800 or PN5180A
Line C: Engineering prototypes are marked "Product life cycle status code Before CQS": X  Refrection and assembly location, date code, product version (indicated by mask version), product life cycle status. This line includes the following elements at 8 positions:  1. Diffusion center code 2. Assembly center code 3. RHF-2006 indicator 4. Year code (Y) 1) 5. Week code (W) 2) 6. Week code (W) 2) 7. Mask layout version 8. (Product life cycle status code "Before CQS") X  PN5180 (customer qualification samples)  Line A:  PN5180A  Cine B1:  6 characters: Diffusion Batch ID and assembly sequence ID  blank  Line C: Customer qualification samples are marked as CQS: X or Y  Blank  Scharacters: diffusion and assembly location, date code, product version (indicated by mask version), product life cycle status. This line includes the following elements at 8 positions: 1. Diffusion center code 2. Assembly center code 3. RHF-2006 indicator 4. Year code (Y) 1) 5. Week code (W) 2) 6. Week code (W) 2) 7. Mask layout version 8. (Product life cycle status code "CQS"): X or Y  PN5180AOHN (released for sale: volume production)  Line A:  PN5180A  Line B1:  6 characters: Diffusion Batch ID	Line B1:	
"Product life cycle status code Before CQS": X  date code, product version (indicated by mask version), product life cycle status. This line includes the following elements at 8 positions:  1. Diffusion center code  2. Assembly center code  3. RHF-2006 indicator  4. Year code (Y) 1)  5. Week code (W) 2)  6. Week code (W) 2)  7. Mask layout version  8. (Product life cycle status code "Before CQS") X   PN5180 (customer qualification samples)  Line A:  Line B1:  6 characters: Diffusion Batch ID and assembly sequence ID  blank  Line C: Customer qualification samples are marked as CQS: X or Y  Base of the code, product version (indicated by mask version), product life cycle status. This line includes the following elements at 8 positions:  1. Diffusion center code  2. Assembly center code  3. RHF-2006 indicator  4. Year code (Y) 1)  5. Week code (W) 2)  6. Week code (W) 2)  7. Mask layout version  8. (Product life cycle status code "CQS"): X or Y  PN5180A0HN (released for sale: volume production)  Line A:  PN5180A  Cine B1:  Carpantar Saturation (indicated by mask version), product life cycle status code "CQS"): X or Y  PN5180A Characters: Diffusion Batch ID	Line B2:	"FW 1.1" or "Z.1 01"
Line A:  Line B1:  6 characters: Diffusion Batch ID and assembly sequence ID  blank  Line C: Customer qualification samples are marked as CQS: X or Y  8 characters: diffusion and assembly location, date code, product version (indicated by mask version), product life cycle status. This line includes the following elements at 8 positions:  1. Diffusion center code 2. Assembly center code 3. RHF-2006 indicator 4. Year code (Y) 1) 5. Week code (W) 2) 6. Week code (W) 2) 7. Mask layout version 8. (Product life cycle status code "CQS"): X or Y  PN5180A0HN (released for sale: volume production)  Line A:  PN5180A  Line B1:  6 characters: Diffusion Batch ID		date code, product version (indicated by mask version), product life cycle status. This line includes the following elements at 8 positions:  1. Diffusion center code 2. Assembly center code 3. RHF-2006 indicator 4. Year code (Y) 1) 5. Week code (W) 2) 6. Week code (W) 2) 7. Mask layout version 8. (Product life cycle status code "Before CQS")
Line B1:  6 characters: Diffusion Batch ID and assembly sequence ID  blank  Line C: Customer qualification samples are marked as CQS: X or Y  8 characters: diffusion and assembly location, date code, product version (indicated by mask version), product life cycle status. This line includes the following elements at 8 positions:  1. Diffusion center code 2. Assembly center code 3. RHF-2006 indicator 4. Year code (Y) 1) 5. Week code (W) 2) 6. Week code (W) 2) 7. Mask layout version 8. (Product life cycle status code "CQS"): X or Y  PN5180A0HN (released for sale: volume production)  Line A:  PN5180A  Line B1:  6 characters: Diffusion Batch ID	PN5180 (customer qualification samples)	
Line B2:  Line C: Customer qualification samples are marked as CQS: X or Y  8 characters: diffusion and assembly location, date code, product version (indicated by mask version), product life cycle status. This line includes the following elements at 8 positions:  1. Diffusion center code 2. Assembly center code 3. RHF-2006 indicator 4. Year code (Y) 1) 5. Week code (W) 2) 6. Week code (W) 2) 7. Mask layout version 8. (Product life cycle status code "CQS"): X or Y  PN5180A0HN (released for sale: volume production)  Line A:  PN5180A  Line B1:  6 characters: Diffusion Batch ID	Line Δ:	DN 15 400 A
Line C: Customer qualification samples are marked as CQS: X or Y  8 characters: diffusion and assembly location, date code, product version (indicated by mask version), product life cycle status. This line includes the following elements at 8 positions:  1. Diffusion center code  2. Assembly center code  3. RHF-2006 indicator  4. Year code (Y) 1)  5. Week code (W) 2)  6. Week code (W) 2)  7. Mask layout version  8. (Product life cycle status code "CQS"): X or Y  PN5180A0HN (released for sale: volume production)  Line A:  PN5180A  Characters: Diffusion Batch ID	LING A.	PN5180A
marked as CQS: X or Y  date code, product version (indicated by mask version), product life cycle status. This line includes the following elements at 8 positions:  1. Diffusion center code 2. Assembly center code 3. RHF-2006 indicator 4. Year code (Y) 1) 5. Week code (W) 2) 6. Week code (W) 2) 7. Mask layout version 8. (Product life cycle status code "CQS"): X or Y  PN5180A0HN (released for sale: volume production)  Line A:  PN5180A  Line B1:  date code, product version (indicated by mask version); includes the following elements at 8 positions: 1. Diffusion center code 2. Assembly center code 3. RHF-2006 indicator 4. Year code (W) 2) 6. Week code (W) 2) 7. Mask layout version 8. (Product life cycle status code "CQS"): X or Y  PN5180A0HN (released for sale: volume production)  Line B1:	-	6 characters: Diffusion Batch ID and assembly
Line A: PN5180A Line B1: 6 characters: Diffusion Batch ID	Line B1:	6 characters: Diffusion Batch ID and assembly sequence ID
Line B1: 6 characters: Diffusion Batch ID	Line B1:  Line B2:  Line C: Customer qualification samples are	6 characters: Diffusion Batch ID and assembly sequence ID  blank  8 characters: diffusion and assembly location, date code, product version (indicated by mask version), product life cycle status. This line includes the following elements at 8 positions:  1. Diffusion center code  2. Assembly center code  3. RHF-2006 indicator  4. Year code (Y) 1)  5. Week code (W) 2)  6. Week code (W) 2)  7. Mask layout version
	Line B1:  Line B2:  Line C: Customer qualification samples are marked as CQS: X or Y	6 characters: Diffusion Batch ID and assembly sequence ID  blank  8 characters: diffusion and assembly location, date code, product version (indicated by mask version), product life cycle status. This line includes the following elements at 8 positions:  1. Diffusion center code  2. Assembly center code  3. RHF-2006 indicator  4. Year code (Y) 1)  5. Week code (W) 2)  6. Week code (W) 2)  7. Mask layout version  8. (Product life cycle status code "CQS"): X or Y
Line B2: Assembly sequence ID, example ".1 04"	Line B1:  Line C: Customer qualification samples are marked as CQS: X or Y  PN5180A0HN (released for sale: volume prod	6 characters: Diffusion Batch ID and assembly sequence ID  blank  8 characters: diffusion and assembly location, date code, product version (indicated by mask version), product life cycle status. This line includes the following elements at 8 positions:  1. Diffusion center code  2. Assembly center code  3. RHF-2006 indicator  4. Year code (Y) 1)  5. Week code (W) 2)  6. Week code (W) 2)  7. Mask layout version  8. (Product life cycle status code "CQS"): X or Y uction)
	Line B1:  Line C: Customer qualification samples are marked as CQS: X or Y  PN5180A0HN (released for sale: volume produline A:	6 characters: Diffusion Batch ID and assembly sequence ID  blank  8 characters: diffusion and assembly location, date code, product version (indicated by mask version), product life cycle status. This line includes the following elements at 8 positions:  1. Diffusion center code  2. Assembly center code  3. RHF-2006 indicator  4. Year code (Y) 1)  5. Week code (W) 2)  6. Week code (W) 2)  7. Mask layout version  8. (Product life cycle status code "CQS"): X or Y

Type number	Marking code
Line C: Release for sale products do not show any X or Y, instead position 8 is left blank	8 characters: diffusion and assembly location, date code, product version (indicated by mask version), product life cycle status. This line includes the following elements at 8 positions:  1. Diffusion center code  2. Assembly center code  3. RHF-2006 indicator  4. Year code (Y) 1)  5. Week code (W) 2)  6. Week code (W) 2)  7. Mask layout version  8. (Product life cycle status "release for sale"): blank

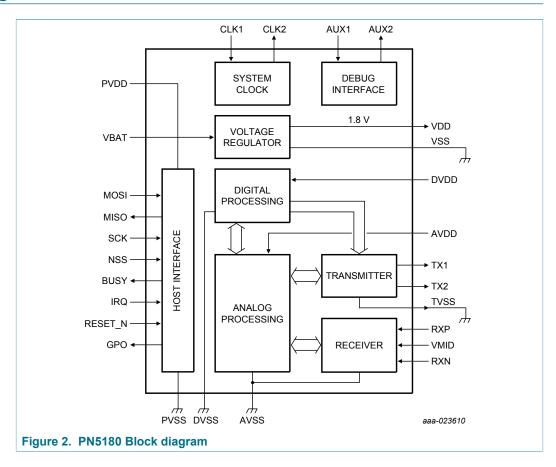
Note that the Firmware of the product PN5180 can be updated. Due to the update capability, the marking of the package does not allow identifying the installed version of the actual programmed firmware. The firmware version can be retrieved from address 0x12 in EEPROM.

# 8.1 Package marking drawing

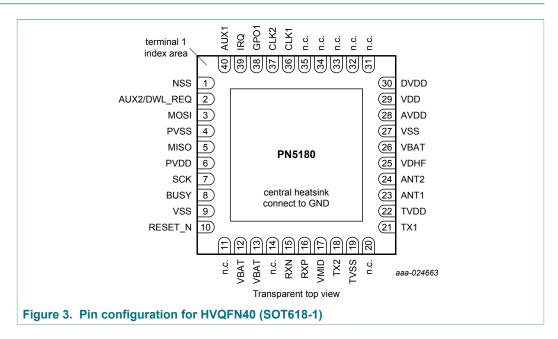


The Marking of the TFBGA version can be found in the data sheet addendum which is available through the NXP DocStore.

# 9 Block diagram



# 10 Pinning information



# 10.1 Pin description

Table 4. Pin description HVQFN40

Symbol	Pin	Туре	Description
NSS	1	I	SPINSS
AUX2 / DWL_REQ	2	I/O	Analog test bus or Download request
MOSI	3	I	SPI MOSI
PVSS	4	supply	Pad ground
MISO	5	0	SPI MISO
PVDD	6	supply	Pad supply voltage
SCK	7	I	SPI Clock
BUSY	8	0	Busy signal
VSS	9	supply	Ground
RESET_N	10	I	RESET, Low active
n.c.	11	-	leave unconnected, do not ground
VBAT	12	supply	Supply Connection, all VBAT mandatory to be connected
VBAT	13	supply	Supply Connection, all VBAT mandatory to be connected
nc / LDO_OUT	14	0	leave unconnected, do not ground / use as 3.3V LDO output
RXN	15	I	Receiver Input
RXP	16	I	Receiver Input
VMID	17	supply	Stabilizing capacitor connection output

Symbol	Pin	Туре	Description
TX2	18	0	Antenna driver output 2
TVSS	19	supply	Antenna driver ground
n.c.	20	-	leave unconnected, do not ground
TX1	21	0	Antenna driver output 1
TVDD	22	supply	Antenna driver supply
ANT1	23	I	Antenna connection 1 for load modulation in card emulation mode (only in case of PLM)
ANT2	24	I	Antenna connection 2 for load modulation in card emulation mode (only in case of PLM)
VDHF	25	supply	Stabilizing capacitor connection output
VBAT	26	supply	Supply Connection, all VBAT mandatory to be connected
VSS	27	supply	Ground
AVDD	28	supply	Analog VDD supply voltage input (1.8 V), connected to VDD
VDD	29	supply	VDD output (1.8 V)
DVDD	30	supply	Digital supply voltage input (1.8 V), connected to VDD
n.c.	31	-	leave unconnected, do not ground
n.c.	32	-	leave unconnected, do not ground
n.c.	33	-	leave unconnected, do not ground
n.c.	34	-	leave unconnected, do not ground
n.c.	35	-	leave unconnected, do not ground
CLK1	36	I	Clock input for crystal. This pin is also used as input for an external generated accurate clock (8 MHz, 12 MHz, 16 MHz, 24 MHz, other clock frequencies not supported)
CLK2	37	0	Clock output (amplifier inverted signal output) for crystal
GPO1	38	0	(double function pin) GPO1, Digital output 1
IRQ	39	0	Interrupt request output, active level configurable
AUX1	40	0	Analog/Digital Test signal

The central heatsink of the HVQFN40 packgage shall be connected to Ground.

The pinning of the TFBGA version can be found in the data sheet addendum which is available through the NXP DocStore.

# 11 Functional description

#### 11.1 Introduction

The PN5180 is a High-Power NFC frontend. It implements the RF functionality like an antenna driving and receiver circuitry and all the low-level functionality to realize an NFC Forum-compliant reader. The PN5180 connects to a host microcontroller with a SPI interface for configuration, NFC data exchange and high-level NFC protocol implementation.

The PN5180 allows different supply voltages for NFC drivers, internal supply and host interface providing a maximum of flexibility.

The chip supply voltage and the NFC driver voltage can be chosen independently from each other.

The PN5180 uses an external 27.12 MHz crystal as clock source for generating the RF field and its internal digital logic. In addition, an internal PLL allows using an accurate external clock source of either 8, 12, 16, 24 MHz. This saves the 27.12 MHz crystal in systems which implement one of the mentioned clock frequencies (e.g. for USB or system clock).

Two types of memory are implemented in the PN5180: RAM and EEPROM.

Internal registers of the PN5180 state machine store configuration data. The internal registers are reset to initial values in case of PowerON, and Hardware-reset and standby.

The RF configuration for dedicated RF protocols is defined by EEPROM data which is copied by a command issued from the host microcontroller - LOAD\_RF\_CONFIG-into the registers of the PN5180. The PN5180 is initialized with EEPROM data for the LOAD\_RF\_CONFIG command which has been tested to work well for one typical antenna. For customer-specific antenna sizes and dedicated antenna environment conditions like metal or ferrite, the pre-defined EEPROM settings can be modified by the user. This allows users to achieve the maximum RF performance from a given antenna design. It is mandatory to use the command LOAD\_RF\_CONFIG for the selection of a specific RF protocol.

The command LOAD\_RF\_CONFIG initializes the registers faster compared to individual register writes.

# 11.2 Power-up and Clock

#### 11.2.1 Power Management Unit

#### 11.2.1.1 Supply Connections and Power-up

The Power Management Unit of the PN5180 generates internal supplies required for operation.

The following pins are used to supply the IC:

- · PVDD supply voltage for the SPI interface and control connections
- · VBAT Supply Voltage input

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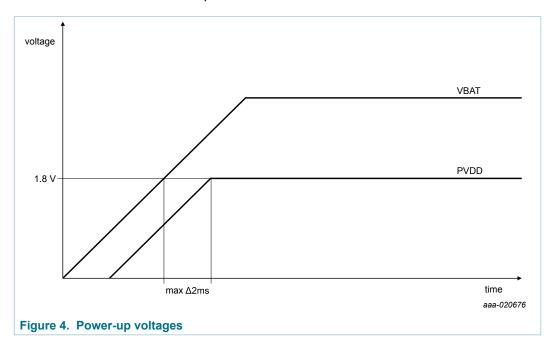
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- TVDD Transmitter supply
- · AVDD Analog supply input, connected to VDD
- DVDD Digital supply input, connected to VDD
- VDD 1.8 V output, to be connected to AVDD and DVDD

Decoupling capacitors shall be placed as close as possible to the pins of the package. Any additional filtering/damping of the transmitter supply, e.g. by ferrite beads, might have an impact on the analog RF signal quality and shall be monitored carefully.

Power-up sequence of the PN5180

- First ramp VBAT, PVDD can immediately follow, latest 2 ms after VBAT reaches 1.8 V.
- There is no timing dependency on TVDD, only that TVDD shall rise equal or later to VBAT.
- · VBAT must be equal or higher than PVDD
- TVDD has no other relationship to VBAT or PVDD



After power-up, the PN5180 is indicating the ability to receive command from a host microcontroller by an IDLE IRQ.

There are configurations in EEPROM, which allow to specify the behavior of the PN5180 after start-up. LPCD (Low-power card detection) and DPC (dynamic power control) are functionalities which are configurable in EEPROM.

#### 11.2.1.2 Power-down

A hard power-down is enabled with LOW level on pin RESET\_N. This low level puts the internal voltage regulators for the analog and digital core supply as well as the oscillator in a low-power state. All digital input buffers are separated from the input pads and clamped internally (except pin RESET\_N itself). IRQ, BUSY, AUX1, AUX2 have an internal pull down resistor which is activated on RESET\_N ==0. All other output pins are switched to high impedance.

To leave the power-down mode, the level at the pin RESET\_N has to be set to HIGH. This high level starts the internal start-up sequence from Power-Down.

#### 11.2.1.3 Standby

The standby mode is entered immediately after sending the instruction SWITCH\_MODE with standby command. All internal current sinks are set to low-power state.

In opposition to the power-down mode, the digital input buffers are not separated by the input pads and keep their functionality. The digital output pins do not change their state.

During standby mode, all registers values, the buffer content and the configuration itself are not kept, exceptions are the registers with addresses 05h(PADCONFIG), 07h(PADOUT) 25h (TEMP\_CONTROL). To leave the standby mode, various possibilities do exist. The conditions for wake-up are configured in the register STBY CFG.

- · Wake-up via Timer
- Wake-up via RF level detector
- Low Level on RESET N
- PVDD disappears

Any host communication (data is not validated) triggers the internal start-up sequence. The reader IC is in operation mode when the internal start-up sequence is finalized, and is indicating this by an IDLE IRQ.

#### 11.2.1.4 Temperature Sensor

The PN5180 implements a configurable temperature sensor. The temperature sensor is configurable by the TEMP CONTROL register (25h).

The Temperature Sensor supports temperature settings for 85 °C, 115 °C, 125 °C and 135 °C.

In case the sensed device temperature is higher than configured, a TEMPSENS\_ERROR IRQ is raised. In case of an TEMPSENS\_ERROR, the Firmware is switching off the RF Field. Additionally host can set the device into standby as response to the raised IRQ.

In case the sensed device temperature is higher than the configured, FW is automatically switching off the RF field in-order to protect the TX drivers and sets the TEMPSENS\_ERROR\_IRQ\_STAT in the IRQ\_STATUS register to 1.

The host can either poll on the TEMPSENS\_ERROR\_IRQ\_STAT or enable the bit TEMPSENS\_ERROR\_IRQ\_EN in IRQ\_ENABLE register to get an interrupt on the IRQ pin.

In addtion, the host can set the device into standby based on the TEMPSENS ERROR IRQ STAT.

This feature is enabled by default. Only the interrupt can be enabled / disabled via the IRQ\_ENABLE register

#### 11.2.2 Reset and start-up time

A constant low level of at least 10  $\mu s$  at the RESET\_N pin starts the internal reset procedure.

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When the PN5180 has finished the start\_up, a IDLE\_IRQ is raised and the IC is ready to receive commands on the host interface.

# 11.2.3 Clock concept

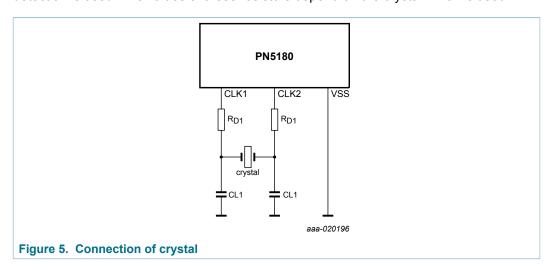
The PN5180 is supplied by an 27.12 MHz crystal for operation. In addition, the internal PLL uses an accurate external clock source of either 8, 12, 16, 24 MHz instead of the crystal.

The clock applied to the PN5180 provides a time basis for the RF encoder and decoder. The stability of the clock frequency, is an important factor for correct operation. To obtain optimum performance, clock jitter must be reduced as much as possible. Optimum performance is best achieved using the internal oscillator buffer with the recommended circuitry.

In card emulation mode, the clock is also required.

If an external clock source of 27.12 MHz is used instead of a crystal, the clock signal must be applied to pin CLK1. In this case, special care must be taken with the clock duty cycle and clock jitter (see Table 137).

The crystal is a component which is impacting the overall performance of the system. A high-quality component is recommended here. The resistor RD1 reduces the start-up time of the crystal. A short start-up time is especially desired in case the Low-Power card detection is used. The values of these resistors depend on the crystal which is used.



### 11.3 Timer and Interrupt system

#### 11.3.1 General Purpose Timer

The Timers are used to measure certain intervals between certain configurable events of the receiver, transmitter and other RF-events. The timer signals its expiration by raising a flag and the value of the timer may be accessed via the register-set.

Three general-purpose timers T0, T1, and T2 running with the PN5180 clock with several start conditions, stop conditions, time resolutions, and maximal timer periods are implemented.

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For automatic timeout handling during MIFARE Classic Authentication Timer2 is blocked during this operation.

In case EMVCo EMD handling is enabled (EMD\_CONTROL register (address 0028h), bit EMD\_ENABLE) Timer1 is automatically restarted when an EMD event occurs.

Timers T0 to T2 has a resolution of 20 bits and may be operated at clock frequencies derived from the 13.56 MHz system clock. Several start events can be configured: start now, start on external RF-field on/off and start on Rx (receive)/Tx (transmit) started/ended. The timers allow reload of the counter value. At expiration of the timers, a flag is raised and an IRQ is triggered.

The clock may be divided by a prescaler for frequencies of:

- 6.78 MHz
- 3.39 MHz
- 1.70 MHz
- 848 kHz
- 424 kHz
- 212 kHz
- 106 kHz
- 53 kHz

## 11.3.2 Interrupt System

#### 11.3.2.1 IRQ PIN

The IRQ\_ENABLE configures, which of the interrupts are routed to the IRQ pin of the PN5180. All of the interrupts can be enabled and disabled independent from each other. The IRQ on the pin can either be cleared by writing to the IRQ\_CLEAR register or by reading the IRQ\_STATUS register (EEPROM configuration). If not all enabled IRQ's are cleared, the IRQ pin remains active.

The polarity of the external IRQ signal is configured by EEPROM in IRQ\_PIN\_CONFIG (01Ah).

#### 11.3.2.2 IRQ STATUS Register

The IRQ\_STATUS register contains the status flags. The status flags cannot be disabled. Status Flag can either be cleared by writing to the IRQ\_CLEAR register or when the IRQ\_STATUS register is read (EEPROM configuration)

The PN5180 indicates certain events by setting bits in the register GENERAL IRQ STATUS and additionally, if activated, on the pin IRQ.

LPCD\_IRQ, GENERAL\_ERROR\_IRQ and HV\_ERROR\_IRQ are non-maskable interrupts.

#### 11.4 SPI Host Interface

The following description of the SPI host interface is valid for the NFC operation mode. The Secure Firmware Download mode uses a different physical host interface handling. Details are described in chapter 12.

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### 11.4.1 Physical Host Interface

The interface of the PN5180 to a host microcontroller is based on a SPI interface, extended by signal line BUSY. The maximum SPI speed is 7 Mbps and fixed to CPOL = 0 and CPHA = 0. Only a half-duplex data transfer is supported. There is no chaining allowed, meaning that the whole instruction has to be sent or the whole receive buffer has to be read out. The whole transmit buffer shall be written at once as well. No NSS assertion is allowed during data transfer.

As the MISO line is per default high-ohmic in case of NSS high, an internal pull-up resistor can be enabled via EEPROM.

The BUSY signal is used to indicate that the PN5180 is not able to send or receive data over the SPI interface.

The host interface is designed to support the typical interface supply voltages of 1.8 V and 3.3 V of CPUs. A dedicated supply input which defines the host interface supply voltage independent from other supplies is available (PVDD). Only a voltage of 1.8 V or 3.3 V is supported, but no voltage in the range of 1.95 V to 2.7 V.

• Master In Slave Out (MISO)

The MISO line is configured as an output in a slave device. It is used to transfer data from the slave to the master, with the most significant bit sent first. The MISO signal is put into 3-state mode when NSS is high.

Master Out Slave In (MOSI)

The MOSI line is configured as an input in a slave device. It is used to transfer data from the master to a slave, with the most significant bit sent first.

Serial Clock (SCK)

The serial clock is used to synchronize data movement both in and out of the device through its MOSI and MISO lines.

• Not Slave Select (NSS)

The slave select input (NSS) line is used to select a slave device. It shall be set to low before any data transaction starts and must stay low during the transaction.

Busy

During frame reception, the BUSY line goes ACTIVE and goes to IDLE when PN5180 is able to receive a new frame or data is available (depending if SET or GET frame is issued). If there is a parameter error, the IRQ is set to ACTIVE and a GENERAL\_ERROR\_IRQ is set.

Both master and slave devices must operate with the same timing. The master device always places data on the MOSI line a half cycle before the clock edge SCK, in order for the slave device to latch the data.

The BUSY line is used to indicate that the system is BUSY and cannot receive any data from a host. Recommendation for the BUSY line handling by the host:

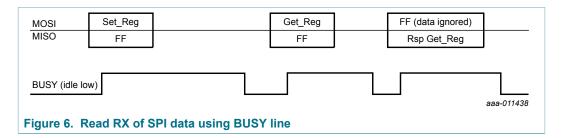
- 1. Assert NSS to Low
- 2. Perform Data Exchange
- 3. Wait until BUSY is high
- 4. Deassert NSS
- 5. Wait until BUSY is low

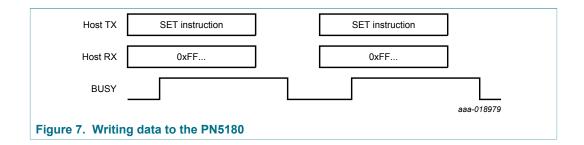
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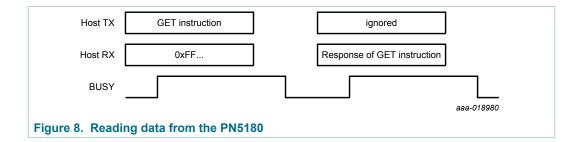
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In order to write data to or read data from the PN5180, "dummy reads" shall be performed. The <u>Figure 8</u> and <u>Figure 9</u> are illustrating the usage of this "dummy reads" on the SPI interface.

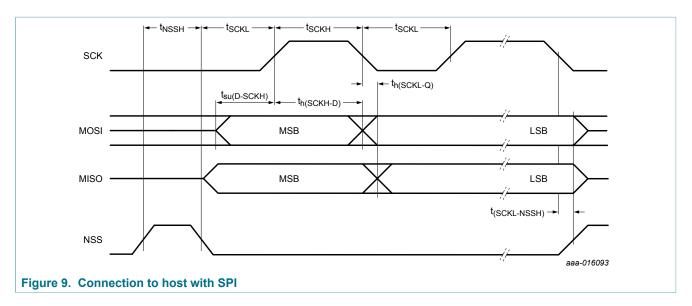






### 11.4.2 Timing Specification SPI

The timing condition for SPI interface is as follows:



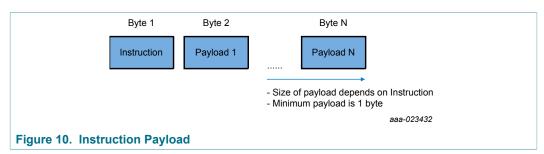
**Remark:** To send more bytes in one data stream, the NSS signal must be LOW during the send process. To send more than one data stream, the NSS signal must be HIGH between each data stream. Any data available to be read from the SPI interface is indicated by the BUSY signal de-asserted.

### 11.4.3 Logical Host Interface

#### 11.4.3.1 Host Interface Command

A Host Interface Command consists of either 1 or 2 SPI frames depending whether the host wants to write or read data from the PN5180. An SPI Frame consists of multiple bytes.

The protocol used between the host and the PN5180 uses 1 byte indicating the instruction code and additional bytes for the payload (instruction-specific data). The actual payload size depends on the instruction used. The minimum length of the payload is 1 byte. This provides a constant offset at which message data begins.



All commands are packed into one SPI Frame. An SPI Frame consists of multiple bytes. No NSS toggles allowed during sending of an SPI frame.

For all 4 byte command parameter transfers (e.g. register values), the payload parameters passed follow the little endian approach (Least Significant Byte first).

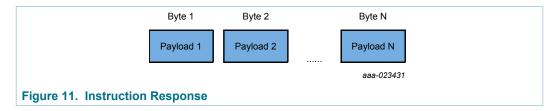
Direct Instructions are built of a command code (1 Byte) and the instruction parameters (max. 260 bytes). The actual payload size depends on the instruction used.

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Responses to direct instructions contain only a payload field (no header). All instructions are bound to conditions. If at least one of the conditions is not fulfilled, an exception is raised.



In case of an exception, the IRQ line of PN5180 is asserted and corresponding interrupt status register contain information on the exception.

#### 11.4.3.2 Transmission Buffer

Two buffers are implemented in the PN5180. The transmission buffer has a buffer size of 260 bytes, the reception buffer has a size of 508 bytes. Both memories buffer the input and output data streams between the host and the internal state machine / contactless UART of the PN5180. Thus, it is possible to handle data streams with lengths of up to 260 bytes for transmission and up to 508 bytes for reception without taking timing constraints into account.

#### 11.4.3.3 Host Interface Command List

Table 5. 1-Byte Direct Commands and Direct Command Codes

Command	Command code	Description
WRITE_REGISTER	0x00	Write one 32bit register value
WRITE_REGISTER_OR_MASK	0x01	Sets one 32bit register value using a 32 bit OR mask
WRITE_REGISTER_AND_MASK	0x02	Sets one 32bit register value using a 32 bit AND mask
WRITE_REGISTER_MULTIPLE	0x03	Processes an array of register addresses in random order and performs the defined action on these addresses.
READ_REGISTER	0x04	Reads one 32bit register value
READ_REGISTER_MULTIPLE	0x05	Reads from an array of max.18 register addresses in random order
WRITE_EEPROM	0x06	Processes an array of EEPROM addresses in random order and writes the value to these addresses
READ_EEPROM	0x07	Processes an array of EEPROM addresses from a start address and reads the values from these addresses
WRITE_TX_DATA	0x08	This instruction is used to write data into the transmission buffer
SEND_DATA	0x09	This instruction is used to write data into the transmission buffer, the START_SEND bit is automatically set.
READ_DATA	0x0A	This instruction is used to read data from reception buffer, after successful reception.
SWITCH_MODE	0x0B	This instruction is used to switch the mode. It is only possible to switch from NormalMode to standby, LPCD or Autocoll.

Command	Command code	Description
MIFARE_AUTHENTICATE	0x0C	This instruction is used to perform a MIFARE Classic Authentication on an activated card.
EPC_INVENTORY	0x0D	This instruction is used to perform an inventory of ISO18000-3M3 tags.
EPC_RESUME_INVENTORY	0x0E	This instruction is used to resume the inventory algorithm in case it is paused.
EPC_RETRIEVE_INVENTORY_RESULT _SIZE	0x0F	This instruction is used to retrieve the size of the inventory result.
EPC_RETRIEVE_INVENTORY_RESULT	0x10	This instruction is used to retrieve the result of a preceding EPC_INVENTORY or EPC_RESUME_INVENTORY instruction.
LOAD_RF_CONFIG	0x11	This instruction is used to load the RF configuration from EEPROM into the configuration registers.
UPDATE_RF_CONFIG	0x12	This instruction is used to update the RF configuration within EEPROM.
RETRIEVE_RF_CONFIG_SIZE	0x13	This instruction is used to retrieve the number of registers for a selected RF configuration
RETRIEVE_RF_CONFIG	0x14	This instruction is used to read out an RF configuration. The register address-value-pairs are available in the response
-	0x15	RFU
RF_ON	0x16	This instruction switch on the RF Field
RF_OFF	0x17	This instruction switch off the RF Field
CONFIGURE_TESTBUS_DIGITAL	0x18	Enables the Digital test bus
CONFIGURE_TESTBUS_ANALOG	0x19	Enables the Analog test bus

The following direct instructions are supported on the Host Interface: Detail Description of the instruction.

# WRITE\_REGISTER - 0x00

#### Table 6. WRITE REGISTER

Payload	Length (byte)	Value/Description		
Command code	1	0x00		
Parameter	1	Register address		
	4	Register content		
Response	-	-		

### **Description:**

This command is used to write a 32-bit value (little endian) to a configuration register.

### **Condition:**

The address of the register must exist. If the condition is not fulfilled, an exception is raised.

#### WRITE REGISTER OR MASK - 0x01

Table 7. WRITE\_REGISTER

Payload	Length (byte)	Value/Description
Command code	1	0x01
Parameter	1	Register address
	4	OR_MASK
Response	-	-

#### **Description:**

This command modifies the content of a register using a logical OR operation. The content of the register is read and a logical OR operation is performed with the provided mask. The modified content is written back to the register.

#### Condition:

The address of the register must exist. If the condition is not fulfilled, an exception is raised.

#### WRITE \_REGISTER\_AND\_MASK - 0x02

Table 8. WRITE\_REGISTER\_AND\_MAKSK

Payload	Length (byte)	Value/Description
Command code	1	0x02
Parameter	1	Register address
	4	AND_MASK
Response	-	-

#### **Description:**

This command modifies the content of a register using a logical AND operation. The content of the register is read and a logical AND operation is performed with the provided mask. The modified content is written back to the register.

#### **Condition:**

The address of the register must exist. If the condition is not fulfilled, an exception is raised.

#### WRITE\_REGISTER\_MULTIPLE - 0x03

Table 9. WRITE REGISTER MULTIPLE

Payload	Length (byte)	Value/Description		
Command code	1	0x03		
Parameter	5210	Array of up to 42 elements {address, action, content}		

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Payload	Length (byte)	Value/Description	
		1 byte	Register address
		1 byte	Action
		4 bytes	Register content
Response	-		-

#### **Description:**

This instruction allows processing actions on multiple addresses with a single command. Input parameter is an array of register addresses, actions, and values (little endian). The command processes this array, register addresses are allowed to be in random order. For each address, an individual ACTION can be defined.

Parameter value is either the REGISTER\_DATA, the OR MASK or the AND\_MASK.

ACTION that can be defined individually for each register address:

- 0x01 WRITE REGISTER
- 0x02 WRITE REGISTER OR MASK
- 0x03 WRITE REGISTER AND MASK

Note: In case of an exception, the operation is not rolled-back, i.e. registers which have been modified until exception occurs remain in modified state. Host has to take proper actions to recover to a defined state.

